

# (19) United States

## (12) Patent Application Publication (10) Pub. No.: US 2023/0232535 A1 Baftiri et al.

Jul. 20, 2023 (43) **Pub. Date:** 

### (54) COMPONENT CARRIER WITH CONNECTED COMPONENT HAVING REDISTRIBUTION LAYER AT MAIN SURFACE

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- (21) Appl. No.: 18/156,373
- (22)Filed: Jan. 18, 2023
- (30)Foreign Application Priority Data

Jan. 19, 2022 (CN) ...... 202210062362.8

#### **Publication Classification**

(51) Int. Cl. H05K 1/18 (2006.01)H05K 3/30 (2006.01)

U.S. Cl. CPC ...... H05K 1/181 (2013.01); H05K 1/185 (2013.01); H05K 3/303 (2013.01)

#### (57)ABSTRACT

A component carrier includes a stack including at least one electrically conductive layer structure and at least one electrically insulating layer structure and a component connected to the stack. The component has a planar redistribution layer at a main surface thereof.

